L Number	Hits	Search Text	DB	Time stamp
1	10055	plasma adj chamber or plasma adj reactor or plasma adj processor	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 05:29
2	198541	chlorine	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 05:30
3	185310	cl	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 05:30
4	327635	chlorine or cl	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 05:31
5	2019	plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 05:31
6	612	(plasma adj chamber or plasma adj reactor or plasma adj processor) and (plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 05:31
7	124	chlorine and ((plasma adj chamber or plasma adj reactor or plasma adj processor) and (plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:24
8	104	(method adj4 igniting) with plasma	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:25
9	56	(method adj4 ignition) with plasma	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:25
10	343	8or ((method adj4 ignition) with plasma)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:25
11	151	((method adj4 igniting) with plasma) or ((method adj4 ignition) with plasma)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:26
12	0	completing adj the and the adj supply and completing adj2 supply	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:28
13	0	completing adj the adj supply	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:29
14	214	supplying adj cl or supplying adj chlorine	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:29
15	0	(((method adj4 igniting) with plasma) or ((method adj4 ignition) with plasma)) and (supplying adj cl or supplying adj chlorine)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:30
16	1592	(plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma) and ignition	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 06:30
17	1	(supplying adj cl or supplying adj chlorine) and ((plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma) and ignition)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:01

18	0	"CL.sub2. "	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:02
19	4091	cl2	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:02
20	4091	CL2	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:03
21	31	cl2 and chf3 and ar	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:23
22	2871	(ignition or ignite) with plasma	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:04
23	5	(cl2 and chf3 and ar) and ((ignition or ignite) with plasma)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:11
24	27450	arc and plasma	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:11
25	45568	arc and coating	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:11
26	12108	(arc and plasma) and (arc and coating)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:11
27	8	(cl2 and chf3 and ar) and ((arc and plasma) and (arc and coating))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:15
28	0	finish adj (supplying adj cl2)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:16
29	0	finish adj (supply adj cl2)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:17
30	0	finish adj3 (supply adj cl2)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:18
31	0	complet$ adj2 (supply adj cl2)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:18
32	0	complet$ adj4 (supply adj cl2)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:22
33	891482	semiconductor or wafer	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:22
34	2871	((ignition or ignite) with plasma) or (plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:23

35	1239	(semiconductor or wafer) and (((ignition or ignite) with plasma) or (plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:23
36	5	(cl2 and chf3 and ar) and ((semiconductor or wafer) and (((ignition or ignite) with plasma) or (plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:23
37	5	((cl2 and chf3 and ar) and ((ignition or ignite) with plasma)) and ((cl2 and chf3 and ar) and ((semiconductor or wafer) and (((ignition or ignite) with plasma) or (plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma))))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:23
38	73	cl2 and chf3	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:23
39	5	(((cl2 and chf3 and ar) and ((ignition or ignite) with plasma)) and ((cl2 and chf3 and ar) and ((semiconductor or wafer) and (((ignition or ignite) with plasma) or (plasma adj ignition or ignite adj3 plasma or ignition adj4 plasma))))) and (cl2 and chf3)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/09/02 07:24